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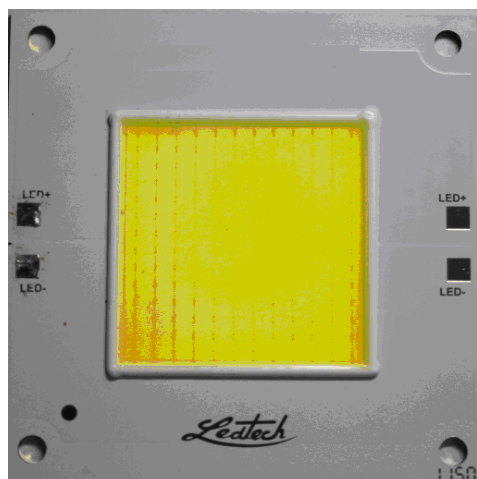
SPECIFICATION

PART NO. : LP30N3-S078

COB 75 x 75 mm TYPE



Approved by	Checked by	Prepared by
王方波	蘇智良	顏保宏



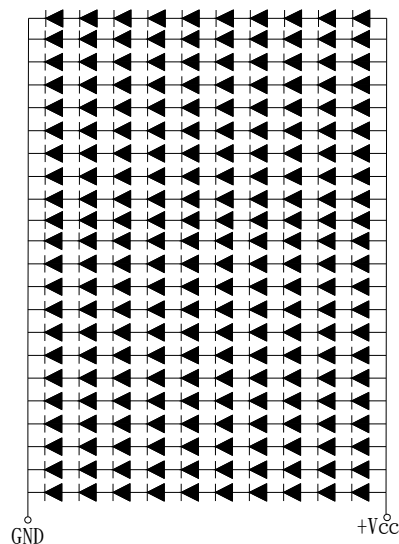
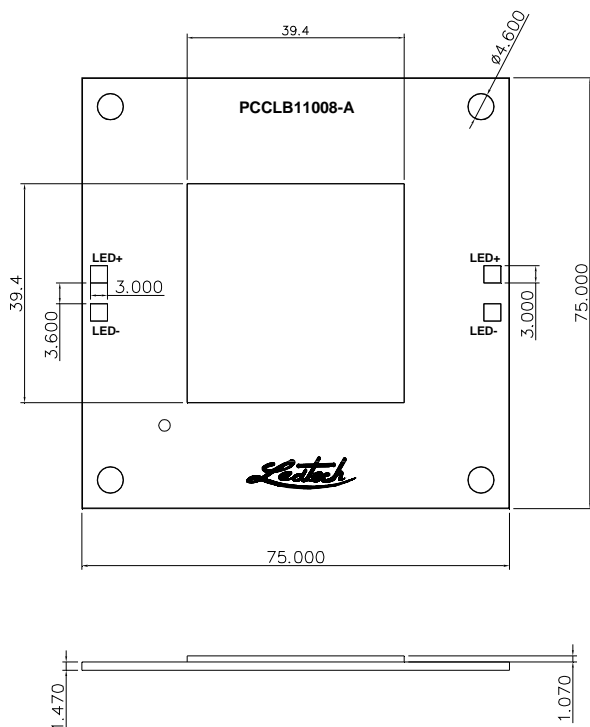
Features

- Pb-Free soldering application
- RoHS compliance
- Multi-Chip package
- High Reliability

Application

- Bay-light module
- Indoor decorative lighting
- Illumination
- Automotive Application
- Architectural Lighting
- Indicator / Decoration

Package Dimensions



Notes:

1. All dimensions are in mm.
2. Tolerance is ± 0.25 mm unless otherwise noted.

Description

Part No.	LED Chip		Lens Color
	Material	Emitting Color	
LP30N3-S078	InGaN/ Sapphire	Neutral White	Orange Diffused

Absolute Maximum Ratings at Ta=25 °C

Parameter	Symbol	Rating	Unit
Power Dissipation	P _D	84	W
D.C. Forward Current	I _f	2400	mA
Peak Current(1/10Duty Cycle,0.1ms Pulse Width.)	I _f (Peak)	2450	mA
Operating Temperature Range	T _{opr.}	-40 to +100	°C
Storage Temperature Range	T _{stg.}	-40 to +100	°C
Solder Heat Resistance	SHR	Hand Soldering:300±5°C for 3 sec.	
Electric Static Discharge Threshold (HBM)	ESD	1000	V

Electrical and Optical Characteristics :

Parameter	Symbol	Condition	Values			Units
			Min.	Typ.	Max.	
Luminous Flux		IF=2.4A		5500		lm
	Rank L2		4800	--	5300	
	Rank L3		5300	--	5800	
Forward voltage		IF=2.4A		31.6		V
	Rank V2		28	--	31	
	Rank V3		31	--	35	
Correlated Color Temperature	CCT	IF=2.4A	3700	--	4300	K
CIE Chromaticity Coordinates: X Axis	X	IF=2.4A	--	0.3818	--	
CIE Chromaticity Coordinates: Y Axis	Y	IF=2.4A	--	0.3797	--	
Reverse Current	I _R	V _r =5V	--	--	50	μA
Color Rendering Index	CRI	IF=2.4A	80	--	--	Ra
Viewing angle at 50% IV		2θ1/2	--	120	--	Deg.

Notes:

1. The dates tested by IS tester.
2. Customer's special requirements are also welcome.

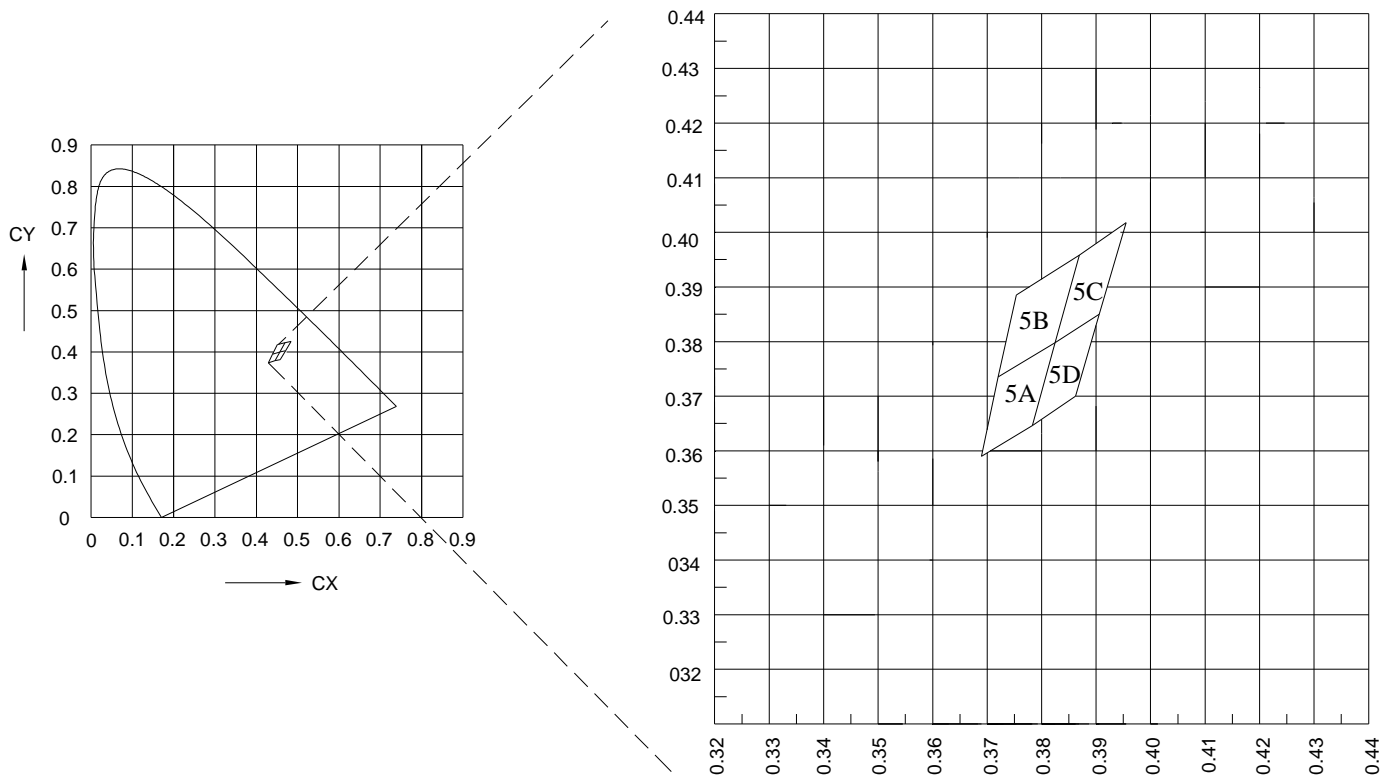
Chromaticity Coordinates Specifications for Bin Grading:

COLOR RANKS (IF=2400mA.Ta=25°C)

BIN	RANK				
5A	X	0.3690	0.3720	0.3825	0.3783
	Y	0.3590	0.3735	0.3798	0.3646
5B	X	0.3720	0.3754	0.3869	0.3825
	Y	0.3735	0.3885	0.3958	0.3798
5C	X	0.3825	0.3869	0.3955	0.3906
	Y	0.3798	0.3958	0.4018	0.3850
5D	X	0.3783	0.3825	0.3906	0.3862
	Y	0.3646	0.3798	0.3850	0.3700

Note: X,Y Tolerance each Bin limit is ± 0.01 .

Chromaticity Coordinates & Bin grading diagram:



Typical Electrical/Optical Characteristic Curves

(25°C Ambient Temperature Unless Otherwise Noted)

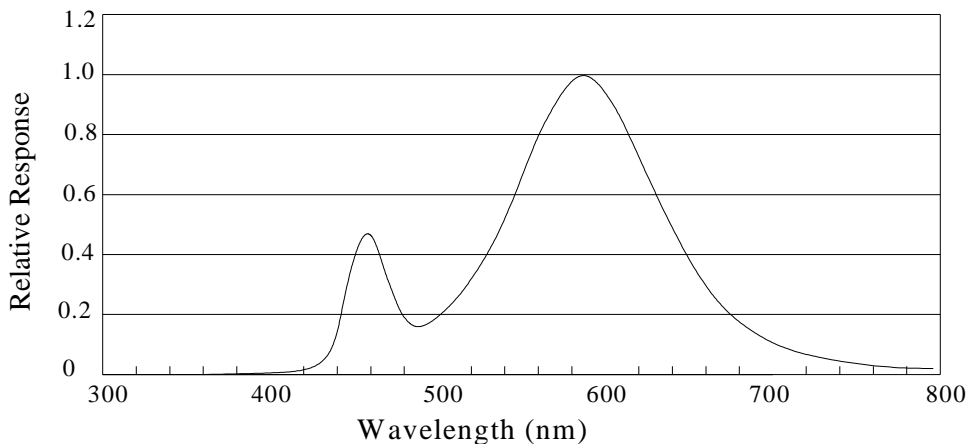
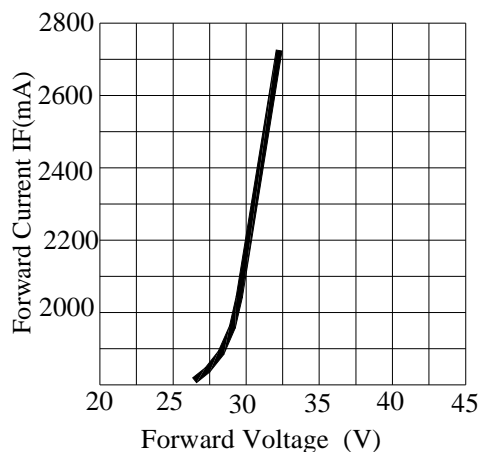
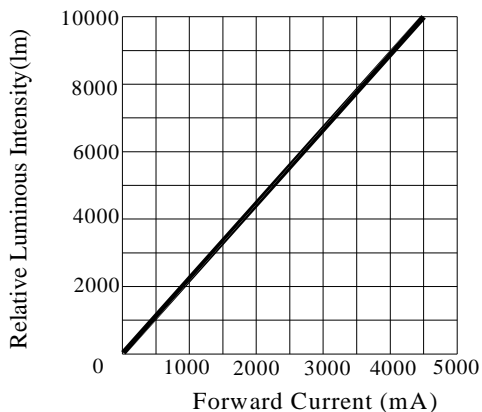


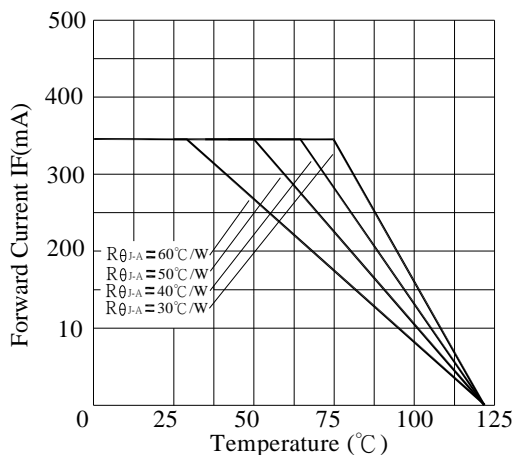
Fig.1 WHITE LED Spectrum VS. WAVELENGTH



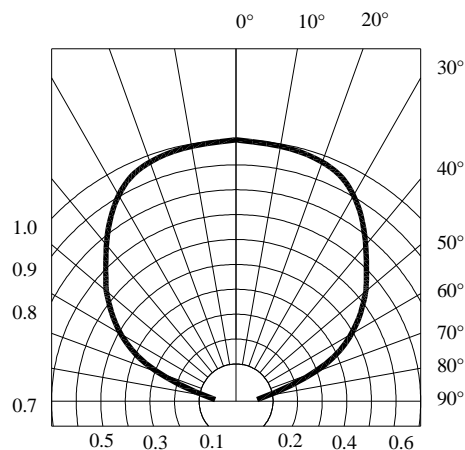
Forward Current VS. Applied Voltage



Forward Current VS. Luminous Intensity



Ambient Temperature VS. Forward Current



Radiation Diagram

Handling of Silicone Resin LEDs

Handling Indications

During processing, mechanical stress on the surface should be minimized as much as possible. Sharp objects of all types should not be used to pierce the sealing compound



Figure 1

In general, LEDs should only be handled from the side. By the way, this also applies to LEDs without a silicone sealant, since the surface can also become scratched.

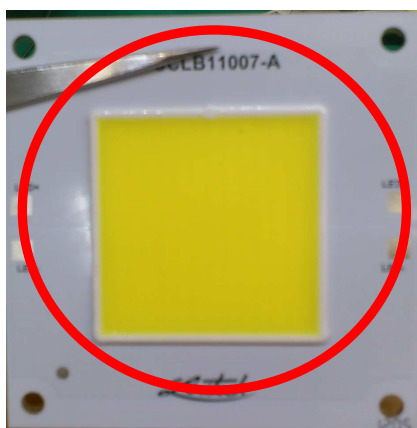


Figure 2

When populating boards in SMT production, there are basically no restrictions regarding the form of the pick and place nozzle, except that mechanical pressure on the surface of the resin must be prevented. This is assured by choosing a pick and place nozzle which is larger than the LED's reflector area.